



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-05-04
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH5R06B	7ZDP*D39S11G	A	SHENZHEN B/E	2016-05-04
Amount		UoM	Unit type	ST ECOPACK Grade
320.00		mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7ZDP*D39511G					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.055	mg	supplier	die	Silicon (Si)	7440-21-3		4.931	mg	975465	15406
				supplier	metallization	Aluminium (Al)	7429-90-5		0.043	mg	8508	134
				supplier	Passivation	Silicon Oxide	7631-86-9		0.014	mg	2770	44
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	396	6
				supplier	back side metallization	Gold (Au)	7440-57-5		0.005	mg	989	16
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	4749	75
				supplier	polymer die coating	Prohimide	proprietary		0.036	mg	7123	113
				supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	987975	512975
Leadframe	Copper & its alloys	166.150	mg	supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1986	1031
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2781	1444
				supplier	metallization	Nickel (Ni)	7440-02-0		1.199	mg	7216	3747
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	42	22
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.444	mg	955075	10763
Soft solder	Solder	3.606	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.090	mg	24958	281
				supplier	solder	Tin (Sn)	7440-31-5		0.072	mg	19967	225
				supplier	wire	Aluminium (Al)	7429-90-5		0.369	mg	1000000	1153
Encapsulation	Other Organic Materials	143.775	mg	supplier	mold compound	Silica, vitreous	60676-86-0		115.883	mg	806002	362134
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		10.064	mg	69999	31450
				supplier	mold compound	Phenol resin	9003-35-4		5.751	mg	40000	17972
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		8.627	mg	60003	26959
				supplier	mold compound	Antimony Trioxide	1309-64-4		1.725	mg	11998	5393
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		1.006	mg	6997	3144
				supplier	mold compound	Carbon black	1333-86-4		0.719	mg	5001	2247
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266